

In the Claims

1. (Original) An information handling system comprising:
plural components operable to process information;
a motherboard interfacing the plural components to communicate the information;
a socket frame coupled to the motherboard;
a socket disposed within the socket frame and coupled to the motherboard, the socket
having plural connectors in electrical communication with the motherboard;
a processor coupled to the socket, the processor having plural connectors aligned to
couple with the socket connectors;
a load plate coupled to the socket frame and having a closed position and an opened
position over the processor, the load plate closed position compressing the
processor connectors into the socket connectors; and
a processor extraction device disposed proximate the load plate and operable to extract
the processor from the socket upon movement of the load plate from a closed to
an open position.
2. (Original) The information handling system of Claim 1 wherein the processor
comprises a central processing unit.
3. (Original) The information handling system of Claim 2 wherein the central
processor unit connectors and socket connectors comprise land grid array connectors.
4. (Currently Amended) The information handling system of Claim 1 wherein the
processor extraction device comprises an adhesive disposed between the load plate and the
processor, the adhesive coupling the load plate to the processor during movement of the load
plate from the closed to the open position.
5. Canceled.
6. Canceled.

7. Canceled.
8. (Original) A method for extracting a processor from a socket, the method comprising:
moving a load plate from a closed position that compresses the processor into the socket to an open position;
activating an extraction device by movement of the load plate from the closed position to the open position; and
extracting the processor from the socket with the activated extraction device.
9. (Original) The method of Claim 8 wherein extracting the processor from the socket further comprises:
coupling the processor to the load plate with an adhesive; and
lifting the processor from the socket by movement of the load plate away from the socket.
10. (Original) The method of Claim 8 wherein extracting the processor from the socket further comprises:
decompressing a spring disposed under the processor by moving the load plate from the closed to the open position; and
pushing the processor from socket by decompression of the spring.
11. (Original) The method of Claim 10 wherein moving the load plate decompresses plural springs disposed around a heat spreader of the processor to apply a substantially even pushing force for extracting the processor from the socket.
12. (Original) The method of Claim 8 wherein extracting the processor from the socket further comprises:
initiating extraction of the processor from the socket with springs aligned to push the processor with the load plate during movement of the load plate from the closed to the open position; and
adhering the processor to the load plate to lift the processor from the socket by translation of lifting motion applied to the load plate.

13. (Original) The method of Claim 8 wherein the processor and socket couple by land grid array connectors.

14. (Original) A system for extracting a processor from a processor socket, the system comprising:

- a socket frame operable to couple to a circuit board proximate a processor socket;
- a load plate coupled to the socket frame and operable to move between a closed position that compresses the processor and an open position that exposes the processor;
- and
- a processor extraction device operable to automatically extract the processor from the socket at movement from the closed position to the open position.

15. (Original) The system of Claim 14 wherein the processor extraction device comprises a spring engaged with the processor to compress with the load plate in the closed position and to apply an extraction force to the processor if the load plate transitions to the opened position.

16. (Original) The system of Claim 14 wherein the processor extraction device comprises plural springs operable to engage with the processor to compress with the load plate in the closed position and to apply an extraction force to the processor if the load plate transitions to the opened position.

17. (Original) The system of Claim 14 wherein the processor extraction device comprises adhesive operable to couple the processor to the load plate.

18. (Original) The system of Claim 17 further comprising one or more springs aligned to bias the processor out of the socket.

19. (Original) The system of Claim 14 further comprising:
a land grid array socket disposed in the socket frame; and
a land grid array processor coupled to the socket.

20. (Original) The system of Claim 19 wherein the processor comprises a central processor unit.

In the Figures

Please amend Figures 1 and 3 as shown in red on the attached sheet.

A Submission of Replacement and Formal Drawings containing this amendment to the Figure has been sent to the Official Draftsman.